Product data sheet

1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD523 (SC-79) ultra small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: I_{F(AV)} ≤ 0.2 A
- Reverse voltage: V_R ≤ 30 V
- Low reverse current: I_R ≤ 30 uA
- Ultra small and flat lead SMD plastic package
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- · Low current rectification
- · High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- · Reverse polarity protection
- Low power consumption applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I_R	reverse current	V _R = 10 V	-	2.5	30	μΑ
V_R	reverse voltage	T _j = 25 °C	-	-	30	V

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]		
2	А	anode	1 2 SC-79 (SOD523)	K ∏ A sym001

[1] The marking bar indicates the cathode.



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6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
RB521S30-Q		plastic, surface-mounted package; 2 leads; 1.2 mm x 0.8 mm x 0.6 mm body	SOD523

7. Marking

Table 4. Marking codes

Type number	Marking code
RB521S30-Q	ZB

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _R	reverse voltage	T _j = 25 °C		-	30	V
I _{F(AV)}	average forward current	δ = 0.5; f = 20 kHz; square wave; $T_{amb} \le$ 120 °C	[1]	-	0.2	А
		δ = 0.5; f = 20 kHz; square wave; $T_{sp} \le$ 140 °C		-	0.2	А
I _{FSM}	non-repetitive peak forward current	t_p = 8.3 ms; half sine wave; JEDEC method; $T_{j(init)}$ = 25 °C	[2]	-	1	А
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[3] [4]	-	275	mW
			[1] [4]	-	420	mW
			[5] [4]	-	500	mW
T _j	junction temperature			-	150	°C
T _{amb}	ambient temperature			-55	150	°C
T _{stg}	storage temperature			-65	150	°C

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [2] T_i = 25 °C Prior to surge
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Reflow soldering is the only recommended soldering method.
- [5] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

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9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	[1] [2] [3]	-	-	455	K/W
			[1] [4] [3]	-	-	300	K/W
			[1] [5] [3]	-	-	250	K/W
R _{th(j-sp)}	thermal resistance from junction to solder point		[6]	-	-	90	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Reflow soldering is the only recommended soldering method.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [5] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [6] Soldering point of cathode tab.

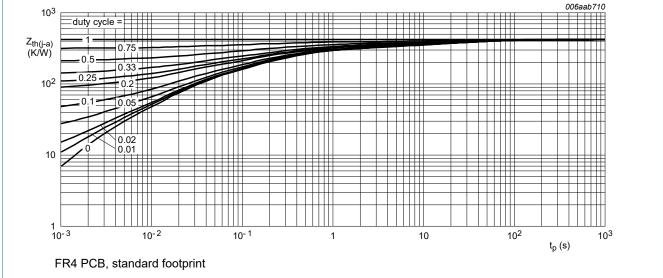
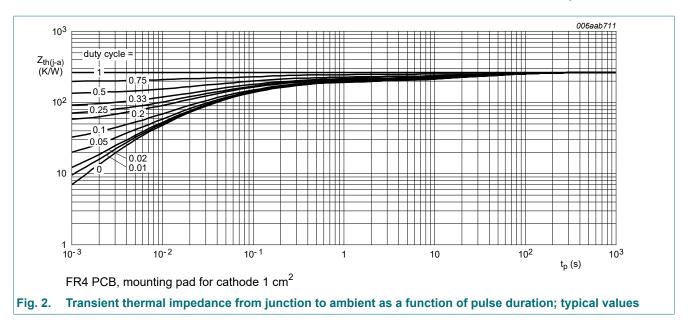


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

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10. Characteristics

Table 7. Characteristics

 T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _F	forward voltage	I _F = 0.1 mA	[1]	-	130	190	mV
		I _F = 1 mA	[1]	-	190	250	mV
		I _F = 10 mA	[1]	-	255	300	mV
		I _F = 100 mA	[1]	-	355	410	mV
		I _F = 200 mA	[1]	-	420	500	mV
I _R	reverse current	V _R = 10 V		-	2.5	30	μΑ
C _d	diode capacitance	V _R = 1 V; f = 1 MHz		-	20	25	pF

[1] Pulsed test: $t_p \le 300 \ \mu s; \ \delta \le 0.02$

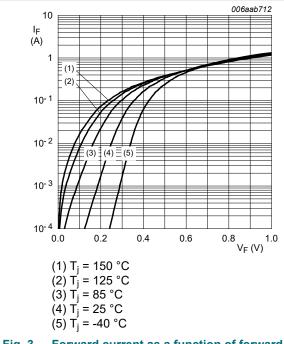


Fig. 3. Forward current as a function of forward voltage; typical values

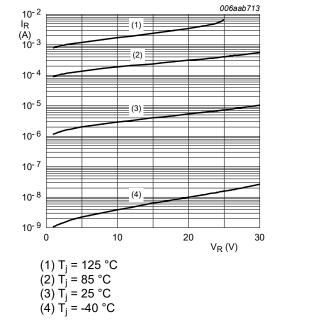


Fig. 4. Reverse current as a function of reverse voltage; typical values

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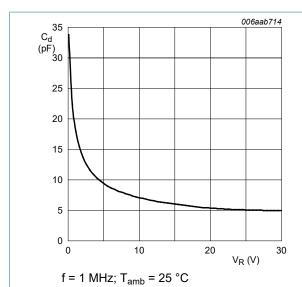
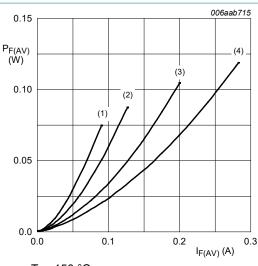
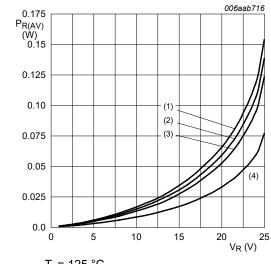


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



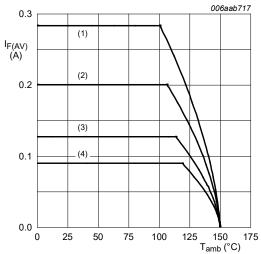
 $T_i = 150 \,{}^{\circ}\text{C}$ $(1) \delta = 0.1$ $(2) \delta = 0.2$ $(3) \delta = 0.5$ $(4) \delta = 1$

Average forward power dissipation as a function of average forward current; typical values



T_i = 125 °C $(1) \delta = 1$ $(2) \delta = 0.9$ $(3) \delta = 0.8$ $(4) \delta = 0.5$

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T_i = 150 °C $(1) \delta = 1$; DC

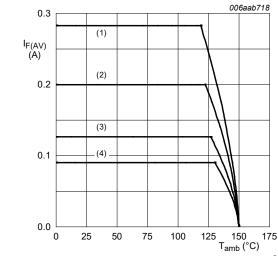
(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values

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FR4 PCB, mounting pad for cathode 1 cm^2

 $T_i = 150 \, ^{\circ}C$

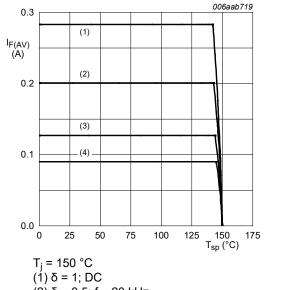
 $(1) \delta = 1; DC$

(2) $\delta = 0.5$; f = 20 kHz

(3) $\delta = 0.2$; f = 20 kHz

(4) $\delta = 0.1$; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



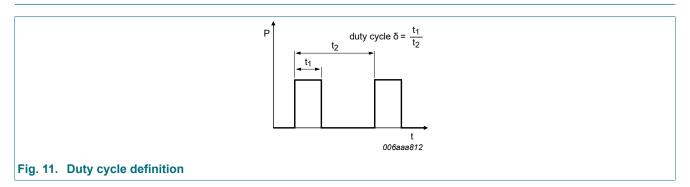
(2) δ = 0.5; f = 20 kHz

(3) δ = 0.2; f = 20 kHz

 $(4) \delta = 0.1$; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

11. Test information



The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

 $I_{RMS}=I_{F(AV)}$ at DC

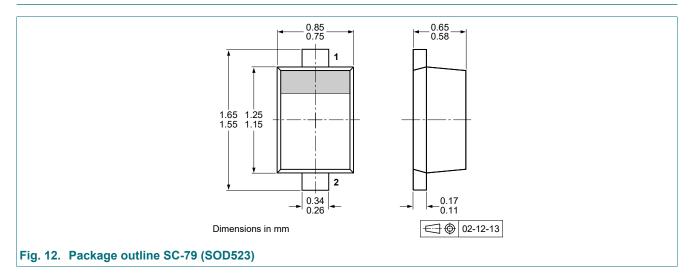
 $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current

Quality information

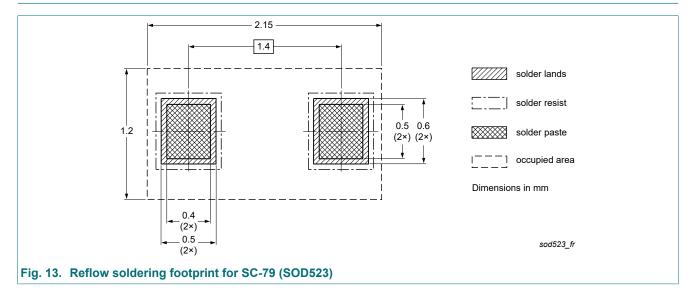
This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

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12. Package outline



13. Soldering



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14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
RB521S30-Q v.1	20230420	Product data sheet	-	-

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15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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